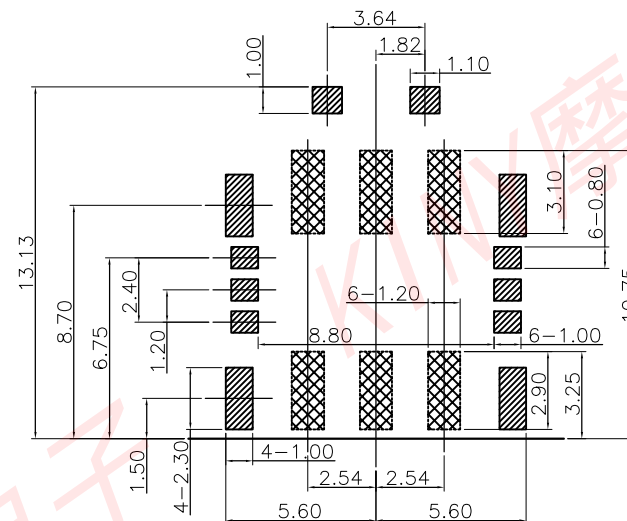
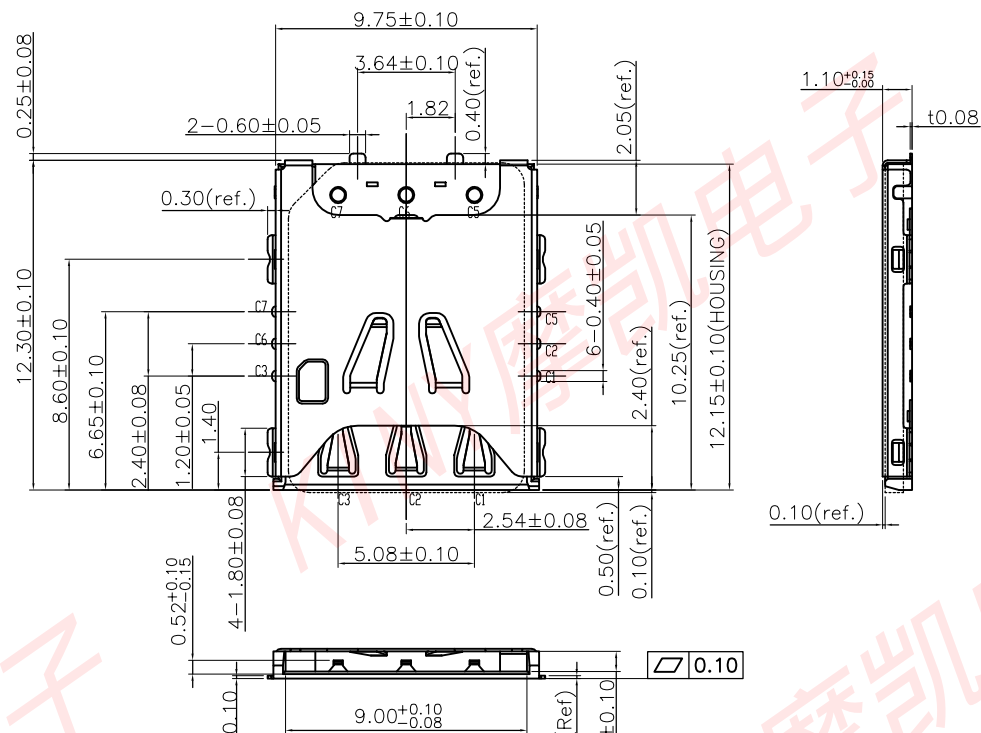


\* 所有原料材质, 生产制程, 电镀必须符合IPC要求

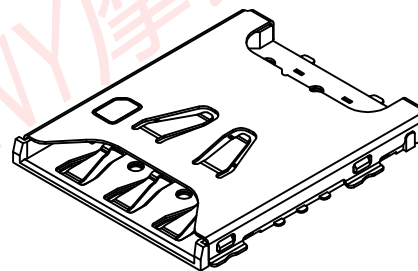


Recommended PCB Layout  
Top View (Tolerance ±0.05)



-  Pad Area
-  Via and Trace keepout Area
-  PCB Edge

NOTE:

1. Material:
  - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
  - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
  - 1-3 Cover: SUS304-H T=0.10±0.03mm
2. Plating:
  - 2-1 Contact terminal:
    - Contact area: Gold 1u" Min.
    - Solder area: Gold 0.8u" Min.
    - Underplating: Ni overall 50u" Min.
  - 2-2 Cover:
    - Underplating: Ni overall 50u" Min.
    - Solder area: Gold 0.8u" Min.
3. Specification:
  - 3-1. Current Rating : 0.5mA AC/DC max.
  - 3-2. Voltage Rating : 125V AC/DC
  - 3-3. Ambient Temperature Range : -20°C~+60°C
  - 3-4. Storage Temperature Range : -40°C~+70°C
  - 3-5. Ambient Humidity Range : 95% R.H. Max.
  - 3-6. Contact Resistance: 100m max.
  - 3-7. Insulation Resistance: 1000M min./500VDC



X0	----	NEW RELEASE	Aaron	2023.01.07
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				

		东莞市摩凯电子有限公司			
DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : NS110-T1151-01	CHECK: DATE:	DRAWING NO. : D-NS110-T1151-01	APPROVED: DATE:	SCALE: 1:1
				DWG ID: C D	REV.: X0
					PAGE: 1 OF 1